

Customer No.: 31561
Application No.: 10/709,954
Docket NO.: 11530-US-PA

REMARKS

In response to the Office Action, mailed on June 30, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-11, drawn to an electrical package, classified in class 257, subclass 778. Please cancel the following two groups without waiver, prejudice or disclaimer:

1. Group II, claims 12-21, drawn to method of manufacturing an electrical package, classified in class 438, subclass 15+;
2. Group III, claims 22-30, drawn to an electrical package substrate, classified in class 361, subclass 1+.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date: *July 27, 2005*

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